PHOTORESIST

HARP[™] PMMA and HARP-C[™] Copolymer

High Aspect Ratio PMMA and Copolymer for e-Beam Lithography

HARP[™] & HARP-C[™] RESIST SERIES

1000 HARP eB

- Highest Mw (molecular weight) PMMA polymer
- Manufactured in Anisole
- Best resolution & contrast PMMA
- Competes with 950 PMMA

500 HARP eB

- PMMA Polymer with mid-range Mw
- Faster throughput versus 1000 HARP eB
- Manufactured in Anisole
- Competes with 495 PMMA

HARP-C

- MMA/MAA (methyl methacrylate/methacrylic acid) copolymer
- Manufactured in Ethyl Lactate
- Used in multi-layer process with PMMA
- Competes with MMA(8.5)MAA

DESCRIPTION

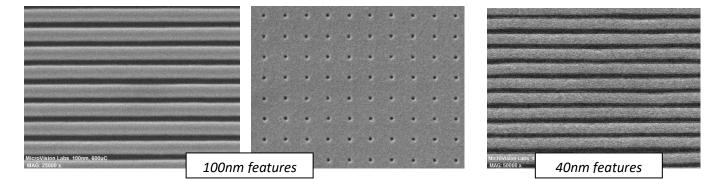
HARP PMMA (polymethyl methacrylate) resist is designed for high resolution direct write e-Beam lithography. When combined with HARP-C copolymer the HARP multi-layer system is ideal for T-gate manufacture. HARP PMMA has excellent adhesion to a wide variety of substrates, and is used as a protective coating layer for wafer thinning and sacrificial layers.

APPLICATIONS

- e-beam direct write lithography
- Multi-layer T-gate manufacture
- X-Ray LIGA
- Protective Coating for wafer thinning

SAFE SOLVENT

HARP PMMA products are manufactured in safe solvents (anisole and ethyl lactate).



SUBSTRATE

HARP PMMA adheres to a variety of substrates including; silicon, gold, aluminum, chromium and copper. Proper substrate cleaning (with O2 plasma) and dehydration bakes can improve adhesion.

SPIN COAT

Film thickness is targeted using the spin speed curves on the following page. Coat program includes a 5-10 second spread cycle. Spin time at final speed is 45 seconds. Spin curves are determined using 6 inch Si and static dispense of approximately 3ml of photoresist.

SOFT BAKE

Recommended soft-bake on contact hotplate:

HARP PMMA 180 °C for 2 min.

HARP-C Copolymer 150 °C for 90 sec.

EXPOSURE (SEE DOSING MATRIX)

e-Beam: 100 - 1000 µC/cm²

Energy: 20 – 100 kV source

Example exposure: 1000 HARP at 0.2 - 0.5 μm film thickness

 $600 \ \mu C/cm^2$ using 50kV energy source to obtain 40 nm feature size

DEVELOP

HARP PMMA and Copolymer Series Resists are developed with MIBK / IPA Developer using immersion, puddle, and spray techniques.

Example process (immersion)

- 1. 60 second immersion in MIBK/IPA
- 2. 30 second rinse with IPA
- 3. Spin dry or N2 blow dry

| HARP PMMA Developers | | |
|----------------------|-----------------------------|--|
| MIBK/IPA 1:1 | High resolution and fast | |
| | develop | |
| MIBK/IPA 1:3 | Highest resolution and slow | |
| | develop | |

RINSE & DRY

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Rinse: IPA (Isopropyl alcohol) or DI water to end the development process.

Dry: Blow dry with N2 or bake at 100oC for 60 seconds to remove residual developer & rinse materials.

REMOVAL

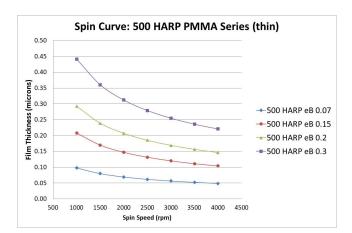
Removal is performed using industry standard removers:

- Acetone & other cleanroom solvents
- NMP-based (n-methyl-2-pyrrolidone)
- O2 plasma
- Glacial acetic acid

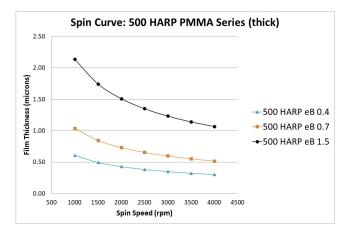
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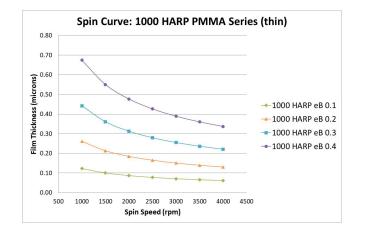
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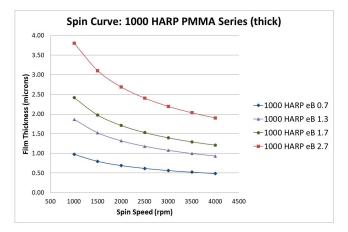
PHOTORESIST MANUFACTURING & INNOVATION

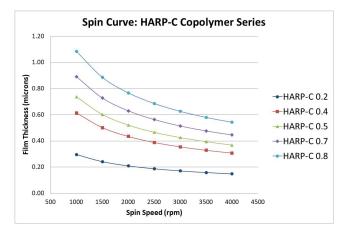


SPIN SPEED CURVES FOR HARP PMMA AND COPOLYMER RESISTS









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PHOTORESIST MANUFACTURING & INNOVATION

FILM THICKNESS @ 2000 RPM AND VISCOSITY FOR HARP PMMA AND COPOLYMER RESISTS

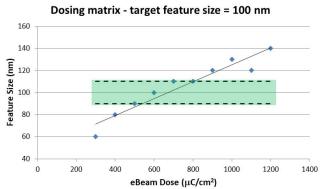
| Product | Approximate FT (microns) at 2000 rpm | Approximate Viscosity (cst) |
|------------------|---|--------------------------------|
| 1000 HARP eB 0.1 | 0.1 | 8 |
| 1000 HARP eB 0.2 | 0.2 | 15 |
| 1000 HARP eB 0.3 | 0.3 | 27 |
| 1000 HARP eB 0.4 | 0.4 | 47 |
| 1000 HARP eB 0.7 | 0.7 | 75 |
| 1000 HARP eB 1.3 | 1.3 | 191 |
| 1000 HARP eB 1.7 | 1.7 | 282 |
| 1000 HARP eB 2.7 | 2.7 | 620 |
| 500 HARP eB 0.07 | 0.07 | 5 |
| 500 HARP eB 0.15 | 0.15 | 9 |
| 500 HARP eB 0.2 | 0.2 | 14 |
| 500 HARP eB 0.3 | 0.3 | 21 |
| 500 HARP eB 0.4 | 0.4 | 32 |
| 500 HARP eB 0.7 | 0.7 | 63 |
| 500 HARP eB 1.5 | 1.5 | 169 |
| HARP-C 0.2 | 0.2 | 9 |
| HARP-C 0.4 | 0.4 | 18 |
| HARP-C 0.5 | 0.5 | 22 |
| HARP-C 0.7 | 0.7 | 30 |
| HARP-C 0.8 | 0.8 | 39 |

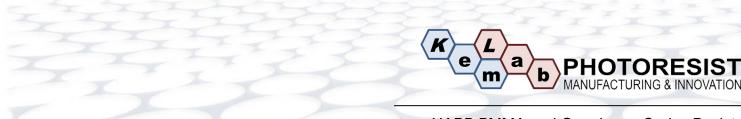


| Target 100 nm | | | | | |
|----------------------------|-------------------|-------------------------------------|------------------------|--|--|
| Dose (µC/cm ²) | Feature Size (nm) | SEM (1000x) | | | |
| 300 | | | Produc | | |
| | 60 | | Tool: | | |
| | | | Film Th | | |
| | | | Acceler | | |
| | | | Develo | | |
| 400 | 80 | | Rinse: | | |
| | | | Ontime | | |
| | | | Optima Dece D | | |
| 500 | 90 | | Dose R | | |
| | | | | | |
| | | | 160 — | | |
| 600 | 100 | | 140 — | | |
| | | | Eastrice Size (mm) 120 | | |
| | | | ize (n | | |
| | | | 5 100 — | | |
| 700 | 110 | | – 08 eatr | | |
| | | | 60 — | | |
| | | | 40 — | | |
| 800 | 110 | and the second second second second | 0 | | |
| | | | | | |
| | | | | | |
| 900 | 120 | | | | |
| 500 | 120 | | | | |
| | | | | | |
| | | | | | |
| 1000 | 130 | | | | |

DOSING MATRIX

| Process | | |
|-----------------------|---|--|
| Product: | 1000 HARP eB 0.3 | |
| Tool: | Raith EBPG5000 | |
| Film Thickness: | 0.3 microns | |
| Accelerating Voltage: | 50 kV | |
| Develop: | 60 sec immersion in MIBK/IPA 1:3 | |
| Rinse: | IPA | |
| | | |
| Optimal Dose: | 600 μC/cm ² | |
| Dose Range (+/-10%) | $500 \mu\text{C/cm}^2$ - $800 \mu\text{C/cm}^2$ | |





PROCESSING ENIVIRONMENT

For best results, use HARP PMMA and Copolymer Series Resists in a controlled room temperature environment of 68 – 77°F (20-25°C) is recommended.

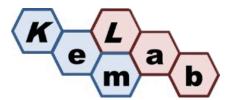
STORAGE

Avoid light and store in an upright airtight container at room temperature. Do not refrigerate. Keep resist away from oxidizers, acids, bases and sources or ignition. Shelf life is 18 months from date of manufacture.

HANDLING & DISPOSAL CONSIDERATIONS

Consult the SDS for handling and appropriate PPE. HARP PMMA contains a combustible liquid; keep away from ignition sources, heat, sparks and flames. HARP PMMA materials are compatible with typical waste streams used with photoresist processing. It is the user's responsibility to dispose in accordance with all local, state, and federal regulations.

DISCLAIMER: The information is based on KemLab's experience and is, to the best of our knowledge, accurate and true. We make no guarantee or warranty, expressed or implied, regarding the information, use, handling, storage, or possession of these products, or the application of any process described herein or the results desired, since the conditions of use and handling of these products are beyond our control.



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